AMENDMENTS TO THE SPECIFICATION

Kindly amend the Specification, on page 14, as follows:

BRIEF DESCRIPTION OF THE DRAWINGS

Fig. 1 is a schematic top view of an inventive circuit arrangement according to an embodiment of the present invention.

Fig. 2 is a representative cross-sectional view of an inventive circuit arrangement according to the embodiment in Fig. 1 along section line I-I ~~another embodiment of the present invention~~.

Fig. 3 is a perspective view of a partial port conductor removed from a ~~in a~~ circuit arrangement in a half-bridge topology according to Fig. 1 as shown from perspective B-B ~~another embodiment of the present invention~~.

Fig. 4 is a schematic top view of an inventive circuit arrangement according to an alternative construction ~~another embodiment~~ of the present invention.

Fig. 5 is a schematic top view of an inventive circuit arrangement according to an alternative construction ~~another embodiment~~ of the present invention.

Kindly amend the Specification, on page 19 last para. to page 20, as follows:

Additionally referring now to Figs. 2 and 3, wherein Fig. 2 depicts a representative cross-sectional view of the assembly taken along line II in Fig. 1, and Fig. 3 represents a partial view of a DC port conductor 20B construction from view-point B-B in Fig. 1, and wherein the DCB substrate consists not only of ceramic substrate 10 and circuit-friendly ribbon connectors 12 arranged on its top surface, but also of a usually-shaped holohedral metal lamination 11 on the underside of ceramic substrate 10, applied by the same method, in the same thickness and made of the same metal as the ribbon connectors 12. On the top surface of substrate 10, opposite metal lamination 11, power semiconductor components 13 are soldered to respective circuit-friendly ribbon connectors 12.